



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-05-12
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Contact Phone *	Refer to Supplier comment section	Contact Email *	Refer to Supplier comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC58NH90C3RME0X	B95Z*FC92BAQ	B	1054	2020-05-12
Amount	UoM	Unit type	ST ECOPACK Grade	
1035.0	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SACN38855	Tin/Silver/Copper (Sn/Ag/Cu)	Copper Alloy	DM00703051	


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Package Designator	Size	Nbr of instances	Shape	
Not Applicable	17.00,17.00,1.70	302	shape	
Comment	FPBGA 17X17X1.8 302			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirement without any exemptions	TRUE
2 - Product(s) meets EU ELV requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.533	die - substrate - solder balls	515
Bisphenol A	0.305	substrate	295

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Homogeneous Material (mg)	Application - Homogeneous Material	ppm in Homogeneous Material

Material Composition Declaration						Mfr Item Name	B95Z*FC92BAQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	35.927	mg	supplier	die	Silicon(Si)	7440-21-3		33.904	mg	943691	32757
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.239	mg	6652	230
				supplier	metallisation	Copper(Cu)	7440-50-8		0.750	mg	20876	725
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.003	mg	84	3
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.127	mg	3535	123
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.021	mg	585	20
				supplier	metallisation	Tungsten(W)	7440-33-7		0.004	mg	111	4
				supplier	passivation	Silicon Oxide	7631-86-9		0.879	mg	24466	849
Substrate	M-015 Other organic materials	413.869	mg	supplier	laminate	Fiber glass	65997-17-3		96.796	mg	233881	93523
				supplier	laminate	Bisphenol F type epoxy resin	9003-36-5		41.440	mg	100128	40039
				supplier	laminate	Bismaleimide (B)	105391-33-1		30.210	mg	72994	29188
				supplier	laminate	Triazine (T)	25722-66-1		30.143	mg	72832	29124
				supplier	laminate	Aluminium hydroxide	21645-51-2		1.337	mg	3230	1292
				supplier	laminate	Zinc hydroxide	20427-58-1		0.267	mg	647	258
				supplier	laminate	Calcium sulfate	7778-18-9		0.669	mg	1616	646
				supplier	SVHC	BPA	80-05-7		0.305	mg	737	295
				supplier	laminate	Amorphous silica	7631-86-9		9.702	mg	23442	9374
				supplier	laminate	other	proprietary		3.348	mg	8090	3235
				supplier	laminate	Oxiranemethanamine compound	110656-67-2		0.323	mg	780	312
				supplier	laminate	Epoxyde bisphenol A resin	25068-38-6		0.696	mg	1682	672
				supplier	laminate	Barium sulfate	7727-43-7		8.722	mg	21074	8427
				supplier	laminate	polymerized Biphenyl resin	85954-11-6		3.425	mg	8276	3309
				supplier	laminate	Talc containing no asbestiform fibers	14807-96-6		2.108	mg	5093	2037
				supplier	laminate	Methoxymethylethoxy propanol	34590-94-8		2.082	mg	5031	2012
				supplier	metallisation	Copper(Cu)	7440-50-8		181.764	mg	439182	175617
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.452	mg	1092	437
				supplier	metallisation	Gold(Au)	7440-57-5		0.080	mg	193	77
				Die attach	M-015 Other organic materials	7.082	mg	supplier	glue	Silver(Ag)	7440-22-4	
supplier	glue	Ditrimethylolpropane tetraacrylate	94108-97-1						1.275	mg	180034	1232
supplier	glue	Diglycidyl phenyl allyl ether	EC 417-470-1						0.213	mg	30076	206
supplier	glue	Mequinol	150-76-5						0.021	mg	2965	20
Bonding wire	M-004 Copper and its alloys	1.280	mg	supplier	wire	Copper(Cu)	7440-50-8		1.243	mg	971094	1201
				supplier	wire	Palladium(Pd)	7440-05-3		0.037	mg	28906	36
encapsulation	M-015 Other organic materials	381.127	mg	supplier	mold compound	Silica vitreous	60676-86-0		310.619	mg	815001	300115
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		38.113	mg	100000	36824
				supplier	mold compound	Phenol resin	205830-20-2		19.056	mg	49999	18412
				supplier	mold compound	Magnesium dihydroxide	1309-42-8		0.381	mg	1000	368
				supplier	mold compound	Quartz	14808-60-7		9.528	mg	25000	9206
				supplier	mold compound	Carbon black	1333-86-4		3.430	mg	9000	3314
solder balls	Solder	195.715	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		182.698	mg	933490	176520
				supplier	solder alloy	Silver(Ag)	7440-22-4		7.438	mg	38004	7186
				supplier	solder alloy	Copper(Cu)	7440-50-8		1.566	mg	8001	1513
				supplier	solder alloy	Nickel(Ni)	7440-02-0		0.078	mg	399	75
				supplier	solder alloy	Antimony(Sb)	7440-36-0		0.020	mg	102	19
				supplier	solder alloy	Bismuth(Bi)	7440-69-9		3.915	mg	20004	3783